Title (en)

METHOD FOR PRODUCING CHIPS, ESPECIALLY FOR SIM CARDS,IN A SERIES.

Title (de)

VERFAHREN ZUR SERIENHERSTELLUNG VON CHIPS, INSBESONDERE FÜR SIM-KARTEN

Title (fr)

PROCEDE DE FABRICATION DE PUCES EN SERIE, NOTAMMENT POUR DES CARTES SIM

Publication

EP 1316062 A1 20030604 (DE)

Application

EP 01960678 A 20010818

Priority

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- EP 0109550 W 20010818
- EP 00119162 A 20000905
- EP 00119163 A 20000905
- EP 00121636 A 20001004

Abstract (en)

[origin: EP1187065A2] The method involves producing software, installing the software on a chip and applying chip-carrier related and user-related personalization data to the chip. The chip-carrier related data are applied to the chip and the user-related personalization data are applied separately in a later production step. Independent claims are also included for the following: an arrangement for testing wafers, an arrangement for manufacturing chip modules, an arrangement for testing chip modules, an arrangement for embedding chip modules in a carrier and an arrangement for personalizing chips embedded in a carrier.

IPC 1-7

G06K 19/07

IPC 8 full level

G06K 17/00 (2006.01); **G06K 19/07** (2006.01); **G06K 19/077** (2006.01)

CPC (source: EP US)

G06K 17/00 (2013.01 - EP US); **G06K 19/07** (2013.01 - EP US); **G06K 19/07716** (2013.01 - EP US); **G06K 19/07743** (2013.01 - EP US)

Citation (search report)

See references of WO 0221434A1

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EP 1187065 A2 20020313; **EP 1187065 A3 20020731**; AU 8210301 A 20020322; EP 1316062 A1 20030604; US 2004015612 A1 20040122; WO 0221434 A1 20020314

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